



Docket No.: M4065.0222/P222-B  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Tongbi Jiang

Application No.: 10/667,391 Confirmation No.: 1655

Filed: September 23, 2003 Art Unit: 2812

For: METHOD OF MAKING A CENTER BOND  
FLIP CHIP SEMICONDUCTOR CARRIER Examiner: S. B. Geyer

**AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. 1.312**

MS Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

Prior to issuance of the patent, applicant respectfully requests entry on this amendment under 37 C.F.R. 1.312 for the above-captioned patent application.

**Amendments to the Specification** begin on page 2 of this paper.

**Remarks/Arguments** begin on page 3 of this paper.